

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







Low-Voltage CMOS Hex Inverter

With 5 V-Tolerant Inputs

The 74LVC04A is a high performance hex inverter operating from a 1.2 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A $V_{\rm I}$ specification of 5.5 V allows 74LVC04A inputs to be safely driven from 5 V devices if $V_{\rm CC}$ is less than 5.0 V.

Current drive capability is 24 mA at the outputs.

Features

- Designed for 1.2 V to 3.6 V V_{CC} Operation
- 5.0 V Tolerant Inputs Interface Capability With 5.0 V TTL Logic
- 24 mA Output Sink and Source Capability
- Near Zero Static Supply Current (10 μA) Substantially Reduces System Power Requirements
- ESD Performance: Human Body Model >2000 V Machine Model >200 V
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

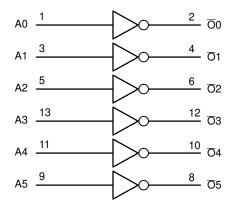


Figure 1. Logic Diagram



ON Semiconductor®

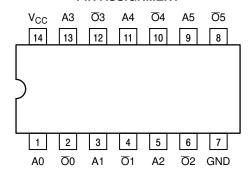
www.onsemi.com





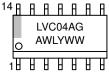
SOIC-14 NB D SUFFIX CASE 751A TSSOP-14 DT SUFFIX CASE 948G

PIN ASSIGNMENT

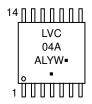


14-Lead (Top View)

MARKING DIAGRAMS



SOIC-14 NB



TSSOP-14

A = Assembly Location

WL, L = Wafer Lot
YY, Y = Year
WW, W = Work Week
G or = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

PIN NAMES

Pins	Function
An	Data Inputs
Ōn	Outputs

TRUTH TABLE

An	Ōn
L	H
H	L

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +6.5		V
VI	DC Input Voltage	$-0.5 \le V_1 \le +6.5$		V
V _O	DC Output Voltage	$-0.5 \le V_{O} \le V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	V
I _{IK}	DC Input Diode Current	-50	V _I < GND	mA
I _{OK}	DC Output Diode Current	-50	V _O < GND	mA
		+50	V _O > V _{CC}	mA
Io	DC Output Source/Sink Current	±50		mA
I _{CC}	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C
T _L	Lead Temperature, 1 mm from Case for 10 Seconds	T _L = 260		°C
TJ	Junction Temperature Under Bias	T _J = 135		°C
$\theta_{\sf JA}$	Thermal Resistance (Note 2)	SOIC = 85 TSSOP = 100		°C/W
MSL	Moisture Sensitivity		Level 1	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Units
V _{CC}	Supply Voltage Operating Functional	1.65 1.2		3.6 3.6	V
VI	Input Voltage	0		5.5	٧
V _O	Output Voltage HIGH or LOW State 3–State	0		V _{CC} 5.5	V
I _{OH}	$ \begin{array}{l} \text{HIGH Level Output Current} \\ \text{V}_{\text{CC}} = 3.0 \text{ V} - 3.6 \text{ V} \\ \text{V}_{\text{CC}} = 2.7 \text{ V} - 3.0 \text{ V} \end{array} $			-24 -12	mA
I _{OL}	LOW Level Output Current $V_{CC} = 3.0 \text{ V} - 3.6 \text{ V}$ $V_{CC} = 2.7 \text{ V} - 3.0 \text{ V}$			24 12	mA
T _A	Operating Free–Air Temperature	-40		+125	°C
Δt/ΔV	Input Transition Rise or Fall Rate V _{CC} = 1.65 V to 2.7 V V _{CC} = 2.7 V to 3.6 V	0		20 10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

^{1.} I_O absolute maximum rating must be observed.

^{2.} Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 2 ounce copper trace no air flow.

DC ELECTRICAL CHARACTERISTICS

			-40	0°C to +8	5°C	-40	°C to +12	5°C	
Symbol	Parameter	Conditions	Min	Typ (Note 3)	Max	Min	Typ (Note 3)	Max	Unit
VIH	HIGH-level input	V _{CC} = 1.2 V	1.08	-	-	1.08	-	-	V
	voltage	V _{CC} = 1.65 V to 1.95 V	0.65 x V _{CC}	-	-	0.65 x V _{CC}	-	-	
		V _{CC} = 2.3 V to 2.7 V	1.7	ı	-	1.7	-	-	
		V _{CC} = 2.7 V to 3.6 V	2.0	ı	-	2.0	-	-	
V_{IL}	LOW-level input	V _{CC} = 1.2 V	_	ı	0.12	_	-	0.12	V
	voltage	V _{CC} = 1.65 V to 1.95 V	_	-	0.35 x V _{CC}	-	-	0.35 x V _{CC}	
		V _{CC} = 2.3 V to 2.7 V	_	-	0.7	-	-	0.7	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	_	8.0	-	-	0.8	
V _{OH}	HIGH-level output voltage	$V_I = V_{IH}$	or V _{IL}						V
	vollage	$I_O = -100 \mu A;$ $V_{CC} = 1.65 \text{ V to } 3.6 \text{ V}$	V _{CC} - 0.2	-	-	V _{CC} - 0.3	-	1	
		$I_O = -4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	1.2	-	ı	1.05	-	-	
		$I_{O} = -8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	1.8	-	ı	1.65	-	-	
		$I_O = -12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	2.2	-	ı	2.05	-	1	
		$I_O = -18 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.4	-	ı	2.25	-	-	
		$I_O = -24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	2.2	-	ı	2.0	-	1	
VOL	LOW-level output voltage	$V_I = V_{IH}$	or V _{IL}						٧
	voltage	$I_O = 100 \mu A;$ $V_{CC} = 1.65 \text{ V to } 3.6 \text{ V}$	_	-	0.2	-	-	0.3	
		$I_O = 4 \text{ mA}; V_{CC} = 1.65 \text{ V}$	_	-	0.45	-	-	0.65	
		$I_{O} = 8 \text{ mA}; V_{CC} = 2.3 \text{ V}$	_	-	0.6	_	-	0.8	
		$I_{O} = 12 \text{ mA}; V_{CC} = 2.7 \text{ V}$	-	-	0.4	-	-	0.6	
		$I_O = -24 \text{ mA}; V_{CC} = 3.0 \text{ V}$	-	T.	0.55	_	-	8.0	
l _l	Input leakage current	$V_I = 5.5V$ or GND $V_{CC} = 3.6 V$	_	±0.1	±5		±0.1	±20	μΑ
I _{OFF}	Power-off leakage current	V_{I} or $V_{O} = 5.5 \text{ V}$; $V_{CC} = 0.0 \text{ V}$	_	±0.1	±10	_	±0.1	±20	μΑ
I _{CC}	Supply current	$V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 3.6 \text{ V}$	_	0.1	10	-	0.1	40	μΑ
Δl _{CC}	Additional supply current	per input pin; $V_{I} = V_{CC} - 0.6 \text{ V}; I_{O} = 0 \text{ A};$ $V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	-	5	500	-	5	5000	μΑ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. All typical values are measured at $T_A = 25^{\circ}C$ and $V_{CC} = 3.3$ V, unless stated otherwise.

AC ELECTRICAL CHARACTERISTICS ($t_R = t_F = 2.5 \text{ ns}$)

			-40°C to +85°C		-40°C to +125°C				
Symbol	Parameter	Conditions	Min	Typ ¹	Max	Min	Typ ¹	Max	Unit
t _{pd}	Propagation Delay (Note 5)	V _{CC} = 1.2 V	-	14.0	_	-	-	-	ns
		V _{CC} = 1.65 V to 1.95 V	0.5	3.7	8.8	0.5	-	10.2	ns
		V _{CC} = 2.3 V to 2.7 V	0.5	2.2	5.0	0.5	_	5.8	
		V _{CC} = 2.7 V	0.5	2.1	5.5	0.5	_	7.0	
		V _{CC} = 3.0 V to 3.6 V	0.5	2.0	4.5	0.5	_	6.0	
t _{sk(0)}	Output Skew Time (Note 6)	$V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$	-	-	1.0	ı	-	1.5	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Typical values are measured at TA = 25°C and Vcc = 3.3 V, unless stated otherwise.

DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V _{OLP}	Dynamic LOW Peak Voltage (Note 7)	$\begin{array}{c} V_{CC} = 3.3 \text{ V, } C_L = 50 \text{ pF, } V_{IH} = 3.3 \text{ V, } V_{IL} = 0 \text{ V} \\ V_{CC} = 2.5 \text{ V, } C_L = 30 \text{ pF, } V_{IH} = 2.5 \text{ V, } V_{IL} = 0 \text{ V} \end{array}$		0.8 0.6		V
V _{OLV}	Dynamic LOW Valley Voltage (Note 7)	$V_{CC} = 3.3 \text{ V}, C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{ V}, V_{IL} = 0 \text{ V}$ $V_{CC} = 2.5 \text{ V}, C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{ V}, V_{IL} = 0 \text{ V}$		-0.8 -0.6		V

^{7.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

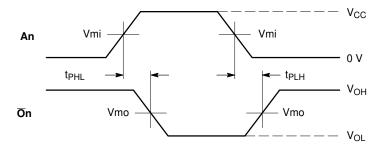
Symbol	Parameter	Condition	Typical	Unit
CIN	Input Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	4.0	pF
Соит	Output Capacitance	V_{CC} = 3.3 V, V_{I} = 0 V or V_{CC}	5.0	pF
C_{PD}	Power Dissipation Capacitance	Per input; V _I = GND or V _{CC}		
	(Note 8)	V _{CC} = 1.65 V to 1.95 V	3.9	
		V _{CC} = 2.3 V to 2.7 V	7.1	
		V _{CC} = 3.0 V to 3.6 V	9.9	

^{8.} C_{PD} is used to determine the dynamic power dissipation (P_D in μW).

 $P_D = C_{PD} \times V_{CC}^2 \times fi \times N + \Sigma (C_L \times V_{CC}^2 \times fo)$ where: fi = input frequency in MHz; fo = output frequency in MHz $C_L = 0$ output load capacitance in pF $V_{CC} = 0$ supply voltage in Volts

N = number of outputs switching $\Sigma(C_L \times V_{CC}^2 \times fo)$ = sum of the outputs.

^{5.} t_{pd} is the same as t_{PLH} and t_{PHL}.
6. Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

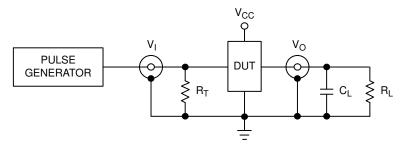


WAVEFORM 1 - PROPAGATION DELAYS

 $t_R = t_F = 2.5 \text{ ns}, 10\% \text{ to } 90\%; f = 1 \text{ MHz}; t_W = 500 \text{ ns}$

	Vcc				
Symbol	3.3 V <u>+</u> 0.3 V	2.7 V	V _{CC} < 2.7 V		
Vmi	1.5 V	1.5 V	Vcc/2		
Vmo	1.5 V	1.5 V	Vcc/2		

Figure 2. AC Waveforms



 $\rm C_L$ includes jig and probe capacitance $\rm R_T = \rm Z_{OUT}$ of pulse generator (typically 50 $\Omega)$

Supply Voltage	Input		Lo	ad
V _{CC} (V)	VI	t _r , t _f	CL	R_L
1.2	V _{CC}	≤ 2 ns	30 pF	1 kΩ
1.65 – 1.95	V _{CC}	≤ 2 ns	30 pF	1 kΩ
2.3 – 2.7	V _{CC}	≤ 2 ns	30 pF	500 Ω
2.7	2.7 V	≤ 2.5 ns	50 pF	500 Ω
3 – 3.6	2.7 V	≤ 2.5 ns	50 pF	500 Ω

Figure 3. Test Circuit

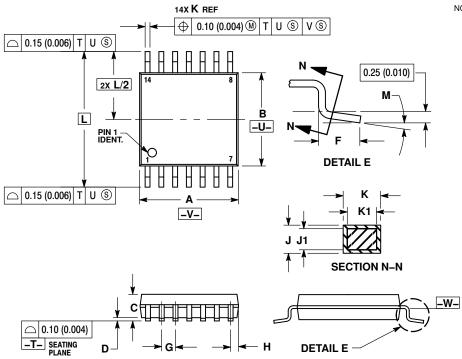
ORDERING INFORMATION

Device	Package	Shipping [†]
74LVC04ADR2G	SOIC-14 NB (Pb-Free)	2500 / Tape & Reel
74LVC04ADTR2G	TSSOP-14 (Pb-Free)	2500 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

TSSOP-14 CASE 948G **ISSUE B**



NOTES:

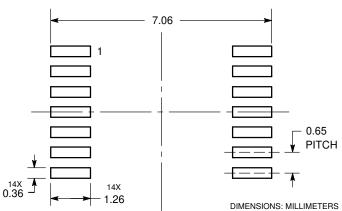
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
 5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- REFERENCE ONLY.

 7. DIMENSION A AND B ARE TO BE
 DETERMINED AT DATUM PLANE –W-.

_				
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20	-	0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026 BSC	
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
Κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40		0.252	BSC
М	0 °	8°	0 °	8 °

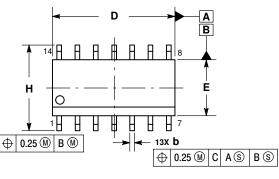
SOLDERING FOOTPRINT*



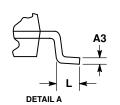
*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

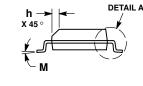
PACKAGE DIMENSIONS

SOIC-14 NB CASE 751A-03 ISSUE K



е





NOTES:

- AOTES.

 1. DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b DOES NOT INCLUDE DAMBAR
- J. DIMENSION & DOES NOT INCLUDE DAMISA PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.

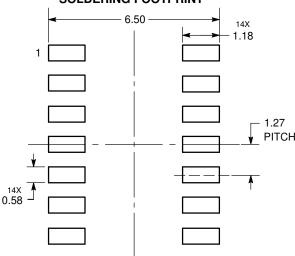
 DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.

 MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- SIDE.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	1.35	1.75	0.054	0.068
A 1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
Е	3.80	4.00	0.150	0.157
е	1.27 BSC		0.050 BSC	
Н	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
М	0 °	7°	0 °	7°

SOLDERING FOOTPRINT*

C SEATING PLANE



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and the an are registered trademarks of Semiconductor Components Industries, LLC (SCILLC) or its subsidiaries in the United States and/or other countries. SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed SCILLC owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of SCILLC's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center

Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative